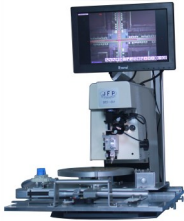


JFP Scriber



MS - 8"

**Manual
Scriber**

- High Accuracy

S-200 - 8"

Automatic Scriber

- Automated alignment
- X Y Theta

S-100 - 4"

Automatic Scriber-Breaker

- Clean facet
- Angle watch
- III-V Semi-Conductor



JFP Microtechnic activities are devoted in sales and services, integrated solutions for assembly, nano- microelectronic and optoelectronic.

Ergonomic, modular, accurate and easy to use, JFP equipments are in use all over the world, from Lab to Industry.

Support our customer's Projects and developp customized :
our high skilled engineering team makes this possible !

***Customers, Solutions and
Quality are our top Priorities !***

JFP Microtechnic , an owner-managed company, with a strong reputation represents over 30 years of experience. The Company is based in Marcoussis, south of Paris.

JFP Microtechnic

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91460 Marcoussis - France

CONTACT :

Phone Number : +33 169 31 35 34

jfp@jfpmicrotechnic.com

www.jfpmicrotechnic.com



The machines which require minimal training to operate

JFP Product line

- ◇ **Wire Bonder WB series**
 - ⇒ WB100e-Wire Bonder
 - ⇒ WB200e/WB201e/Manual/Semi Auto
 - ⇒ WB210/AutoBond Ball Bonder
 - ⇒ MPT Mini Pull Tester
- ◇ **Pick & Place**
 - ⇒ MPS-Manual Placer System
 - ⇒ PP6 Universal Die Bonder
 - ⇒ WB300-Ultrasonic Die Bonder
 - ⇒ PP-One Pick & Place
- ◇ **Laser Bar**
 - ⇒ PP-One-Laser Bar Test
 - ⇒ Laser Bar Stacker-Unstacker
- ◇ **Diamond Scriber**
 - ⇒ MS-Manual Scriber
 - ⇒ S200-8 Scriber
 - ⇒ S100-4 Scriber Breaker

Wire Bonder

JFP WB-100e

Motorized Z-Axis
Wedge & Ball Bonding



JFP WB 200 SERIES

Manual/Semi-Automatic
Ball, Wedge, Bump & Ribbon Bonding
WB200-e/WB201-e

Or Automatic Ball Bonder
WB210

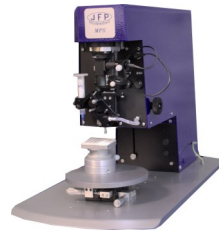


Die Bonder

JFP MPS

Manual Placer System for Lab

- Compact
- High Accuracy



JFP PP6

Universal Die Bonder

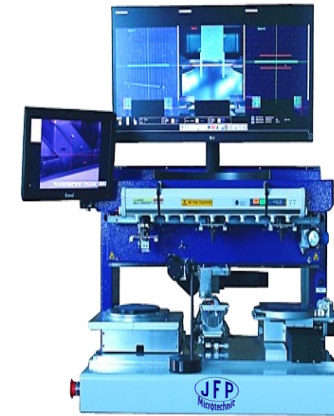
- Full automated process
- Face up & Face down
- Placement of delicate devices



JFP WB300

- Z Automated process

JFP PP-One Manual/Semi-automatic Micro Placer



Picking and Placement of :

- Delicate IC devices
- Laser Diodes /Sensors
- Micro-Mechanical Parts

Flexible Configuration

Laser Bar Stacker

Laser Bar Assembly

Laser Bar Test

- Die Bonding gluing and soldering of chips in pick and place operations

